

away from the planar circuit board, light being transmittable and receivable through the functional front.

2. (original): An assembly as claimed in claim 1, wherein the planar circuit board includes an end portion defining a recess in which the optical transceiver module is disposed.

3. (original): An assembly as claimed in claim 1, wherein the planar substrate includes electrically conductive interconnects for coupling electrical terminals on the optical transceiver module with electrical terminals on the planar circuit board.

4. (original): An assembly as claimed in claim 1, wherein the planar substrate and the planar circuit board are substantially parallel.

5. (original): An assembly as claimed in claim 1, wherein the planar substrate is soldered onto the major surface of the planar circuit board.

6. (original): An assembly as claimed in claim 1, wherein the optical transceiver module is soldered onto the extended portion of the planar substrate.

7. (original): An assembly as claimed in claim 1, wherein the optical transceiver module is mounted on, and the major surface of the planar circuit board faces a same side of the planar substrate.

8. (withdrawn)

9. (withdrawn)

10. (currently amended): A circuit board assembly comprising:
a planar circuit board having a major surface, and a side surface defining a recess,

a planar substrate mounted on the major surface of the circuit board, an extended portion of the planar substrate extending over the recess, and

an optical transceiver module having a functional front through which light is transmittable and receivable, the optical transceiver module being mounted on the extended portion of the substrate so as to be disposed in the recess with the functional front generally perpendicular to the major surface of the planar circuit board and facing away from the planar circuit board.

11. (currently amended): An optical transceiver module package for mounting on a planar circuit board having a major surface and a side surface, the major surface provided with electrical terminals, the optical transceiver module package comprising:

a planar substrate for mounting on the major surface of the circuit board so that an extended portion of the planar substrate extends beyond the side surface,

an optical transceiver module provided with electrical terminals and a functional front through which light is transmittable and receivable, the optical transceiver module being mounted on the extended portion of the substrate adjacent the side surface of the printed circuit board such that the functional front is generally perpendicular to the major surface of the planar circuit board and faces away from the planar circuit board, and

electrically conductive interconnects associated with the planar substrate for coupling the electrical terminals on the optical transceiver module with electrical terminals on the planar circuit board.

12. (currently amended): An optical transceiver module package for mounting on a planar circuit board having a major surface and at least one side surface defining a recess, the major surface provided with electrical terminals, the optical transceiver module package comprising:

a planar substrate for mounting on the major surface of the circuit board so that an extended portion of the planar surface extends over the recess, an optical transceiver module provided with electrical terminals and a functional front through which light is transmittable and receivable, the optical transceiver module being mounted on the extended portion of the substrate so as to be disposed in the recess

with the functional front generally perpendicular to the major surface of the planar circuit board and facing away from the planar circuit board, and electrically conductive interconnects associated with the planar substrate for coupling the electrical terminals on the optical transceiver module with electrical terminals on the planar circuit board.

13. (previously added): An assembly as claimed in claim 1, wherein the optical transceiver module comprises a light emitting diode and a photodiode, packaged together with supporting circuitry to form a self-contained unit.

14. (previously added): An assembly as claimed in claim 13, wherein the optical receiver module comprises a first molded lens shape over the light emitting diode and a second molded lens shape over the photodiode.

15. (previously added): An assembly as claimed in claim 13, wherein the optical transceiver module is an infrared transceiver module.

16. (previously added): An assembly as claimed in claim 2, wherein the side surface of the planar circuit board is a multi-faceted surface bounding the recess on three sides and leaving a fourth side open.

17. (previously added): An assembly as claimed in claim 16, wherein the optical transceiver module comprises a plurality of transceiver lenses which face outwards from the open side of the recess.

18. (previously added): An assembly as claimed in claim 1, wherein the optical transceiver module is surface mounted on the extended portion of the substrate.

19. (new): An assembly as claimed in claim 1, wherein the optical transceiver module further comprises lenses having apexes that define the functional front of the

optical transceiver module and wherein the extended portion of the planar substrate has an edge that is substantially planar with the apexes.

20. (new): An assembly as claimed in claim 1, wherein the optical transceiver module further comprises castellated electrical terminals defined at an edge of the optical transceiver module and the planar substrate comprises electrically conductive interconnects; wherein the castellated electrical terminals are electrically connected to the electrically conductive interconnects by solder joints.